NB2305A

3.3 V Zero Delay Clock Buffer

The NB2305A is a versatile, 3.3 V zero delay buffer designed to distribute high−speed clocks. It accepts one reference input and drives out five low−skew clocks. It is available in a 8 pin package.

The −1H version of the NB2305A operates at up to 133 MHz, and has higher drive than the −1 devices. All parts have on−chip PLL's that lock to an input clock on the REF pin. The PLL feedback is on−chip and is obtained from the CLKOUT pad.

Multiple NB2305A devices can accept the same input clock and distribute it. In this case the skew between the outputs of the two devices is guaranteed to be less than 700 ps.

All outputs have less than 200 ps of cycle−to−cycle jitter. The input and output propagation delay is guaranteed to be less than 350 ps, and the output to output skew is guaranteed to be less than 250 ps.

The NB2305A is available in two different configurations, as shown in the ordering information table. The NB2305AI is the base part. The NB2305AI1H is the high drive version of the −1 and its rise and fall times are much faster than −1 part.

Features

- 15 MHz to 133 MHz Operating Range, Compatible with CPU and PCI Bus Frequencies
- Zero Input − Output Propagation Delay
- Multiple Low−Skew Outputs
- Output−Output Skew Less than 250 ps
- Device−Device Skew Less than 700 ps
- One Input Drives 5 Outputs
- Less than 200 ps Cycle−to−Cycle Jitter is Compatible with Pentium® Based Systems
- Accepts Spread Spectrum Clock at the Input
- Available in 8 Pin, 150 mil SOIC Package and 8 Pin TSSOP 4.4 mm
- 3.3 V Operation, Advanced 0.35 μ CMOS Technology
- Guaranteed Across Commercial and Industrial Temperature Ranges
- These are Pb−Free Devices

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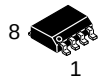
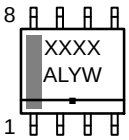
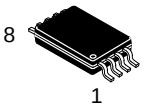
MARKING DIAGRAMS*

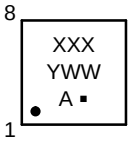


SOIC−8
D SUFFIX
CASE 751





TSSOP−8
DT SUFFIX
CASE 948S



XXXX	= Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
▪	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

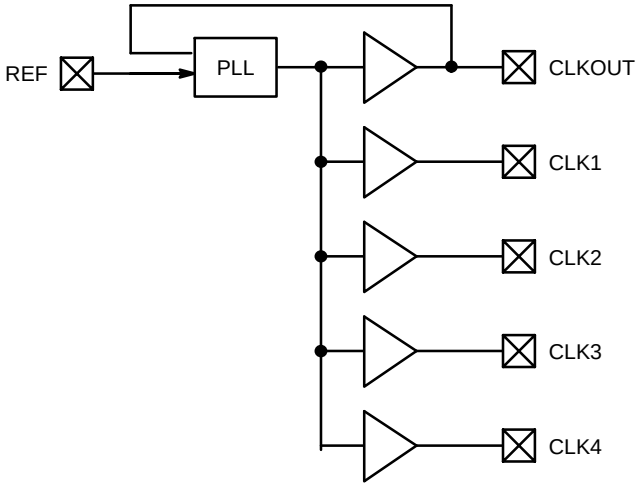


Figure 1. Block Diagram

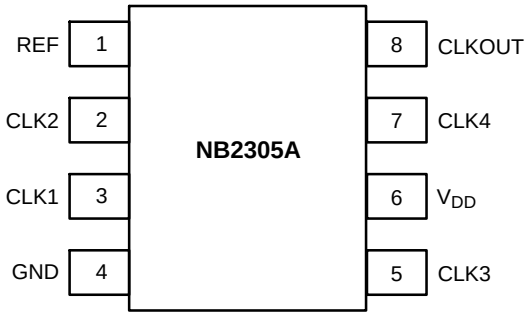


Figure 2. Pin Configuration

Table 1. PIN DESCRIPTION

Pin #	Pin Name	Description
1	REF (Note1)	Input reference frequency, 5 V tolerant input.
2	CLK2 (Note 2)	Buffered clock output.
3	CLK1 (Note 2)	Buffered clock output.
4	GND	Ground.
5	CLK3 (Note 2)	Buffered clock output.
6	V_{DD}	3.3 V supply.
7	CLK4 (Note 2)	Buffered clock output.
8	CLKOUT (Note 2)	Buffered clock output, internal feedback on this pin.

1. Weak pulldown.
2. Weak pulldown on all outputs.

Table 2. MAXIMUM RATINGS

Parameter	Min	Max	Unit
Supply Voltage to Ground Potential	−0.5	+7.0	V
DC Input Voltage (Except REF)	−0.5	V_{DD} + 0.5	V
DC Input Voltage (REF)	−0.5	7.0	V
Storage Temperature	−65	+150	°C
Maximum Soldering Temperature (10 sec)		260	°C
Junction Temperature		150	°C
Static Discharge Voltage (per MIL−STD−883, Method 3015)		>2000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. RECOMMENDED OPERATING CONDITIONS FOR INDUSTRIAL TEMPERATURE DEVICES

Parameter	Description		Min	Max	Unit
V_{DD}	Supply Voltage		3.0	3.6	V
T_A	Operating Temperature (Ambient Temperature)	Industrial Commercial	−40 0	85 70	°C
C_L	Load Capacitance, below 100 MHz			30	pF
C_L	Load Capacitance, from 100 MHz to 133 MHz			10	pF
C_{IN}	Input Capacitance			7	pF

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. ELECTRICAL CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, GND = 0 V, T_A = −40°C to +85°C

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW Voltage (Note 3)			0.8	V
V_{IH}	Input HIGH Voltage (Note 3)		2.0		V
I_{IL}	Input LOW Current	V_{IN} = 0 V		50	μA
I_{IH}	Input HIGH Current	V_{IN} = V_{DD}		100	μA
V_{OL}	Output LOW Voltage	I_{OL} = 8 mA (−1) I_{OL} = 12 mA (−1H)		0.4	V
V_{OH}	Output HIGH Voltage	I_{OH} = −8 mA (−1) I_{OH} = −12 mA (−1H)	2.4		V
I_{DD}	Supply Current (Commercial Temp)	Unloaded outputs at 66.67 MHz, Select inputs at V_{DD}		34	mA
I_{DD}	Supply Current (Industrial Temp)	Unloaded outputs at 100 MHz 66.67 MHz 33 MHz Select inputs at V_{DD} or GND, at Room Temp		50 34 19	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. REF input has a threshold voltage of V_{DD}/2.

Table 5. SWITCHING CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, GND = 0 V, T_A = −40°C to +85°C (Note 4)

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
$1/t_1$	Output Frequency	30 pF load 10 pF load	15 15		100 133	MHz
$1/t_1$	Duty Cycle = (t_2 / t_1) * 100 (−1, −1H) (−1H)	Measured at 1.4 V, F_{OUT} = 66.67 MHz < 50 MHz	40 45	50 50	60 55	%
t_3	Output Rise Time (−1) (−1H)	Measured between 0.8 V and 2.0 V			2.5 1.5	ns
t_4	Output Fall Time (−1) (−1H)	Measured between 2.0 V and 0.8 V			2.5 1.5	ns
t_5	Output−to−Output Skew	All outputs equally loaded			250	ps
t_6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at V_{DD}/2		0	±350	ps
t_7	Device−to−Device Skew	Measured at V_{DD}/2 on the CLKOUT pins of the device		0	700	ps
t_J	Cycle−to−Cycle Jitter	Measured at 66.67 MHz, loaded outputs			200	ps
t_{LOCK}	PLL Lock Time	Stable power supply, valid clock presented on REF pin			1.0	ms

4. All parameters specified with loaded outputs.

Zero Delay and Skew Control

All outputs should be uniformly loaded to achieve Zero Delay between input and output. Since the CLKOUT pin is the internal feedback to the PLL, its relative loading can adjust the input−output delay.

For applications requiring zero input−output delay, all outputs, including CLKOUT, must be equally loaded. Even if CLKOUT is not used, it must have a capacitive load equal to that on other outputs, for obtaining zero−input−output delay.

SWITCHING WAVEFORMS

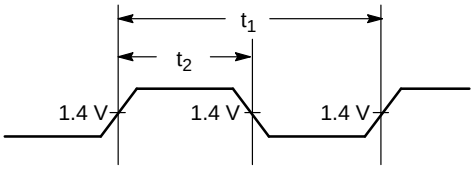


Figure 3. Duty Cycle Timing

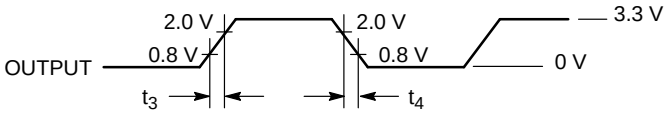


Figure 4. All Outputs Rise/Fall Time

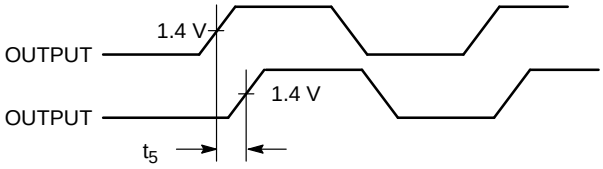


Figure 5. Output − Output Skew

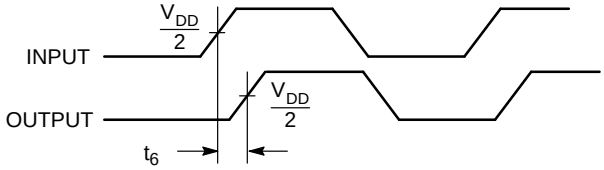


Figure 6. Input − Output Propagation Delay

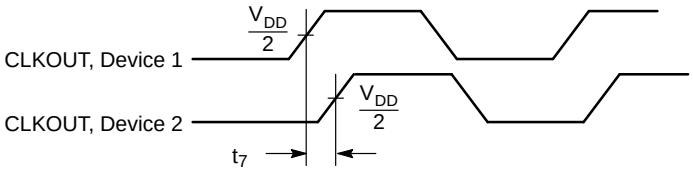


Figure 7. Device − Device Skew

TEST CIRCUITS

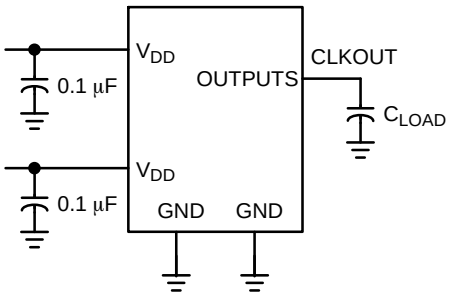


Figure 8. Test Circuit #1

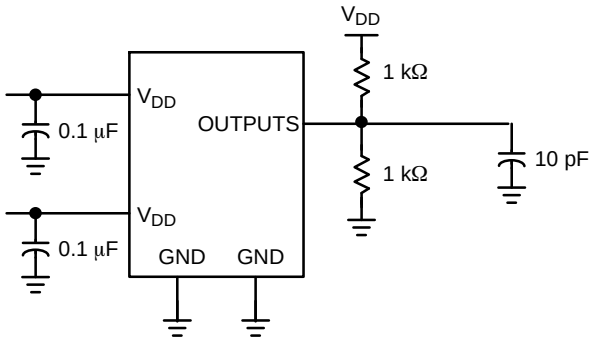


Figure 9. Test Circuit #2
For parameter t_8 (output slew rate) on −1H devices

ORDERING INFORMATION

Device	Marking	Operating Range	Package	Shipping†	Availability
NB2305AI1DG	5I1	Industrial & Commercial	SOIC−8 (Pb−Free)	98 Units / Rail	*Now*
NB2305AI1DR2G	5I1	Industrial & Commercial	SOIC−8 (Pb−Free)	2500 Tape & Reel	*Now*
NB2305AI1HDG	5I1H	Industrial & Commercial	SOIC−8 (Pb−Free)	98 Units / Rail	*Now*
NB2305AI1HDR2G	5I1H	Industrial & Commercial	SOIC−8 (Pb−Free)	2500 Tape & Reel	*Now*
NB2305AI1DTG	5I1	Industrial & Commercial	TSSOP−8 (Pb−Free)	100 Units / Rail	*Now*
NB2305AI1DTR2G	5I1	Industrial & Commercial	TSSOP−8 (Pb−Free)	2500 Tape & Reel	*Now*
NB2305AI1HDTG	5IH	Industrial & Commercial	TSSOP−8 (Pb−Free)	100 Units / Rail	*Now*
NB2305AI1HDTR2G	5IH	Industrial & Commercial	TSSOP−8 (Pb−Free)	2500 Tape & Reel	*Now*

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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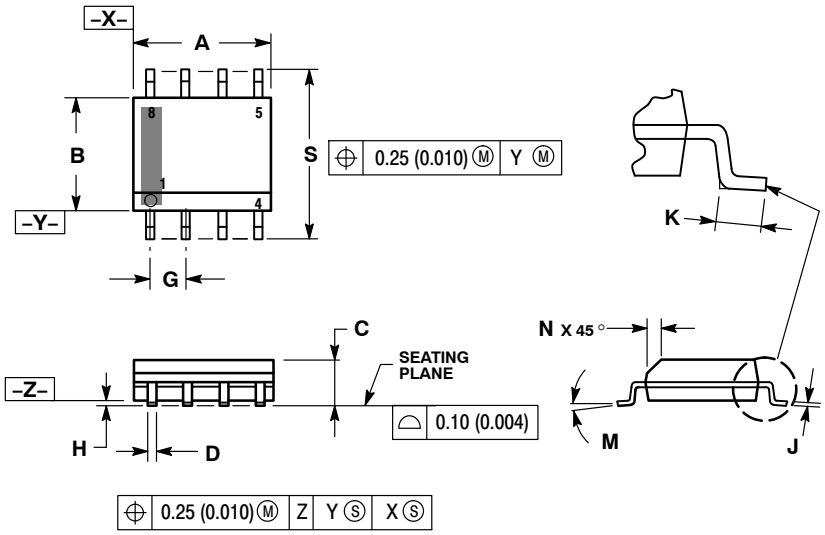
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

SCALE 1:1

SOIC−8 NB
CASE 751−07
ISSUE AK

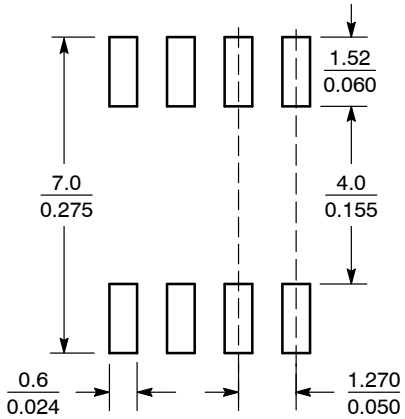
DATE 16 FEB 2011



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

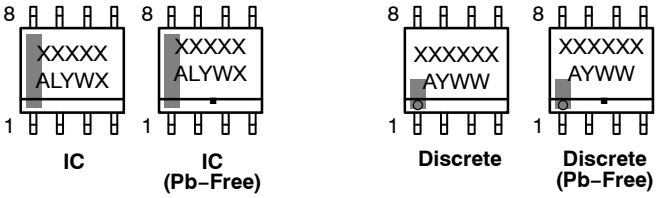
SOLDERING FOOTPRINT*



SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	**98ASB42564B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**SOIC−8 NB**	**PAGE 1 OF 2**

SOIC−8 NB
CASE 751−07
ISSUE AK

DATE 16 FEB 2011

STYLE 1:
PIN 1. EMITTER
2. COLLECTOR
3. COLLECTOR
4. EMITTER
5. EMITTER
6. BASE
7. BASE
8. EMITTER

STYLE 2:
PIN 1. COLLECTOR, DIE, #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. BASE, #2
6. EMITTER, #2
7. BASE, #1
8. EMITTER, #1

STYLE 3:
PIN 1. DRAIN, DIE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. GATE, #2
6. SOURCE, #2
7. GATE, #1
8. SOURCE, #1

STYLE 4:
PIN 1. ANODE
2. ANODE
3. ANODE
4. ANODE
5. ANODE
6. ANODE
7. ANODE
8. COMMON CATHODE

STYLE 5:
PIN 1. DRAIN
2. DRAIN
3. DRAIN
4. DRAIN
5. GATE
6. GATE
7. SOURCE
8. SOURCE

STYLE 6:
PIN 1. SOURCE
2. DRAIN
3. DRAIN
4. SOURCE
5. SOURCE
6. GATE
7. GATE
8. SOURCE

STYLE 7:
PIN 1. INPUT
2. EXTERNAL BYPASS
3. THIRD STAGE SOURCE
4. GROUND
5. DRAIN
6. GATE 3
7. SECOND STAGE Vd
8. FIRST STAGE Vd

STYLE 8:
PIN 1. COLLECTOR, DIE #1
2. BASE, #1
3. BASE, #2
4. COLLECTOR, #2
5. COLLECTOR, #2
6. EMITTER, #2
7. EMITTER, #1
8. COLLECTOR, #1

STYLE 9:
PIN 1. EMITTER, COMMON
2. COLLECTOR, DIE #1
3. COLLECTOR, DIE #2
4. EMITTER, COMMON
5. EMITTER, COMMON
6. BASE, DIE #2
7. BASE, DIE #1
8. EMITTER, COMMON

STYLE 10:
PIN 1. GROUND
2. BIAS 1
3. OUTPUT
4. GROUND
5. GROUND
6. BIAS 2
7. INPUT
8. GROUND

STYLE 11:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

STYLE 12:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 13:
PIN 1. N.C.
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 14:
PIN 1. N−SOURCE
2. N−GATE
3. P−SOURCE
4. P−GATE
5. P−DRAIN
6. P−DRAIN
7. N−DRAIN
8. N−DRAIN

STYLE 15:
PIN 1. ANODE 1
2. ANODE 1
3. ANODE 1
4. ANODE 1
5. CATHODE, COMMON
6. CATHODE, COMMON
7. CATHODE, COMMON
8. CATHODE, COMMON

STYLE 16:
PIN 1. EMITTER, DIE #1
2. BASE, DIE #1
3. EMITTER, DIE #2
4. BASE, DIE #2
5. COLLECTOR, DIE #2
6. COLLECTOR, DIE #2
7. COLLECTOR, DIE #1
8. COLLECTOR, DIE #1

STYLE 17:
PIN 1. VCC
2. V2OUT
3. V1OUT
4. TXE
5. RXE
6. VEE
7. GND
8. ACC

STYLE 18:
PIN 1. ANODE
2. ANODE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. CATHODE
8. CATHODE

STYLE 19:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. MIRROR 2
7. DRAIN 1
8. MIRROR 1

STYLE 20:
PIN 1. SOURCE (N)
2. GATE (N)
3. SOURCE (P)
4. GATE (P)
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 21:
PIN 1. CATHODE 1
2. CATHODE 2
3. CATHODE 3
4. CATHODE 4
5. CATHODE 5
6. COMMON ANODE
7. COMMON ANODE
8. CATHODE 6

STYLE 22:
PIN 1. I/O LINE 1
2. COMMON CATHODE/VCC
3. COMMON CATHODE/VCC
4. I/O LINE 3
5. COMMON ANODE/GND
6. I/O LINE 4
7. I/O LINE 5
8. COMMON ANODE/GND

STYLE 23:
PIN 1. LINE 1 IN
2. COMMON ANODE/GND
3. COMMON ANODE/GND
4. LINE 2 IN
5. LINE 2 OUT
6. COMMON ANODE/GND
7. COMMON ANODE/GND
8. LINE 1 OUT

STYLE 24:
PIN 1. BASE
2. EMITTER
3. COLLECTOR/ANODE
4. COLLECTOR/ANODE
5. CATHODE
6. CATHODE
7. COLLECTOR/ANODE
8. COLLECTOR/ANODE

STYLE 25:
PIN 1. VIN
2. N/C
3. REXT
4. GND
5. IOUT
6. IOUT
7. IOUT
8. IOUT

STYLE 26:
PIN 1. GND
2. dv/dt
3. ENABLE
4. ILIMIT
5. SOURCE
6. SOURCE
7. SOURCE
8. VCC

STYLE 27:
PIN 1. ILIMIT
2. OVLO
3. UVLO
4. INPUT+
5. SOURCE
6. SOURCE
7. SOURCE
8. DRAIN

STYLE 28:
PIN 1. SW_TO_GND
2. DASIC_OFF
3. DASIC_SW_DET
4. GND
5. V_MON
6. VBULK
7. VBULK
8. VIN

STYLE 29:
PIN 1. BASE, DIE #1
2. EMITTER, #1
3. BASE, #2
4. EMITTER, #2
5. COLLECTOR, #2
6. COLLECTOR, #2
7. COLLECTOR, #1
8. COLLECTOR, #1

STYLE 30:
PIN 1. DRAIN 1
2. DRAIN 1
3. GATE 2
4. SOURCE 2
5. SOURCE 1/DRAIN 2
6. SOURCE 1/DRAIN 2
7. SOURCE 1/DRAIN 2
8. GATE 1

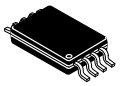
DOCUMENT NUMBER:	**98ASB42564B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	**SOIC−8 NB**		**PAGE 2 OF 2**

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

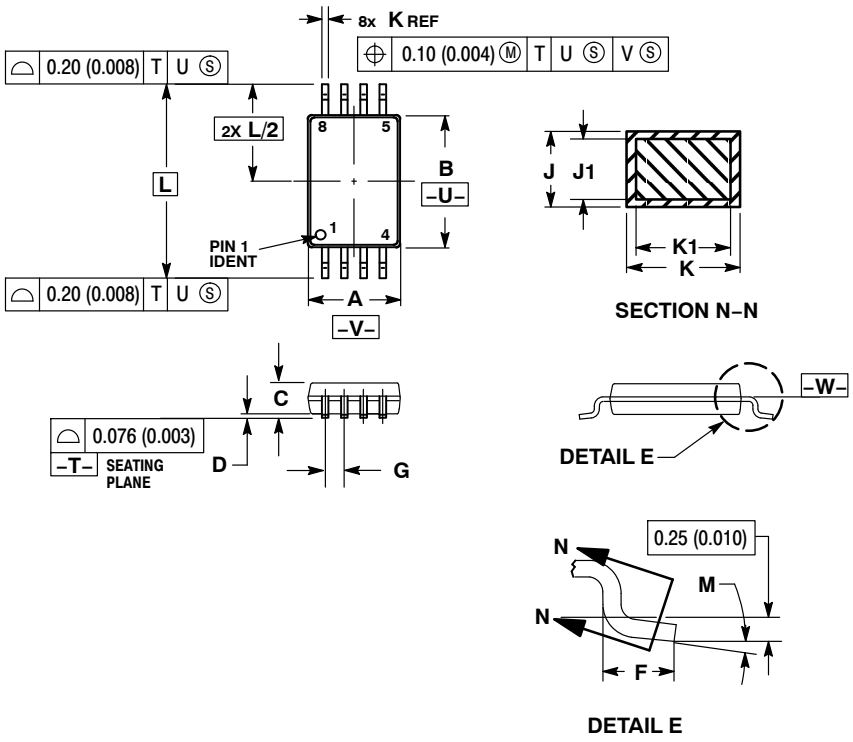
ON Semiconductor®

TSSOP−8
CASE 948S−01
ISSUE C

DATE 20 JUN 2008



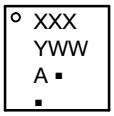
SCALE 2:1



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.10	---	0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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NEW STANDARD:			
DESCRIPTION:	TSSOP−8		PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION.	18 APR 2000
A	ADDED MARKING DIAGRAM INFORMATION. REQ. BY V. BASS.	13 JAN 2006
B	CORRECTED MARKING DIAGRAM PIN 1 LOCATION AND MARKING. REQ. BY C. REBELLO.	13 MAR 2006
C	REMOVED EXPOSED PAD VIEW AND DIMENSIONS P AND P1. CORRECTED MARKING INFORMATION. REQ. BY C. REBELLO.	20 JUN 2008

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